

SM1A53NHU-VB Datasheet N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)				
100	0.0085 at V _{GS} = 10 V	85				
	0.0105 at V _{GS} = 4.5 V	70				

FEATURES

- Trench Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested

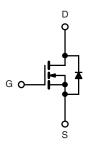
RoHS

APPLICATIONS

- Primary Side Switch
- Isolated DC/DC Converter







N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	100	V		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 25 °C	1-	85		
Continuous Diam Current (1) = 150 C)	T _C = 125 °C	I _D	75 ^a		
Pulsed Drain Current	I _{DM}	300	Α		
Avalanche Current	L = 0.1 mH	I _{AS}	75		
Single Pulse Avalanche Energy ^b	L = U. I IIII	E _{AS}	280	mJ	
Mariana Barra Biratiratirah	T _C = 25 °C	P _D	176	W	
Maximum Power Dissipation ^b	T _A = 25 °C		3.75	VV	
Operating Junction and Storage Temperature I	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Case	Sleady State	R _{thJC}	0.85	1.1	C/VV	

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA 100				V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$			4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C			50		
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 175°C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
		V _{GS} = 10 V, I _D = 20 A		0.0085			
	D	V _{GS} = 4.5 V, I _D = 20 A	0.0105				
Drain-Source On-State Resistance ^a	H _{DS(on)}	V _{GS} = 10 V, I _D =20 A, T _J = 125 °C		0.017		Ω	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$	0.022				
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20A	25			S	
Dynamic ^b							
Input Capacitance	C _{iss}			4000			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		565		pF	
Reverse Transfer Capacitance	C _{rss}			205			
Total Gate Charge ^c	Qg			105	160		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 45 \text{ A}$		17		nC	
Gate-Drain Charge ^c	Q _{gd}			23			
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 20 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 45 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns	
Fall Time ^c	t _f			130	195		
Source-Drain Diode Ratings and Char	acteristics T _C	= 25 °C ^b					
Continuous Current	I _S				85	^	
Pulsed Current	I _{SM}				140	Α	
Forward Voltage ^a	V _{SD}	I _F = 45 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dl/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	7		0.17	0.35	μС	

Notes:

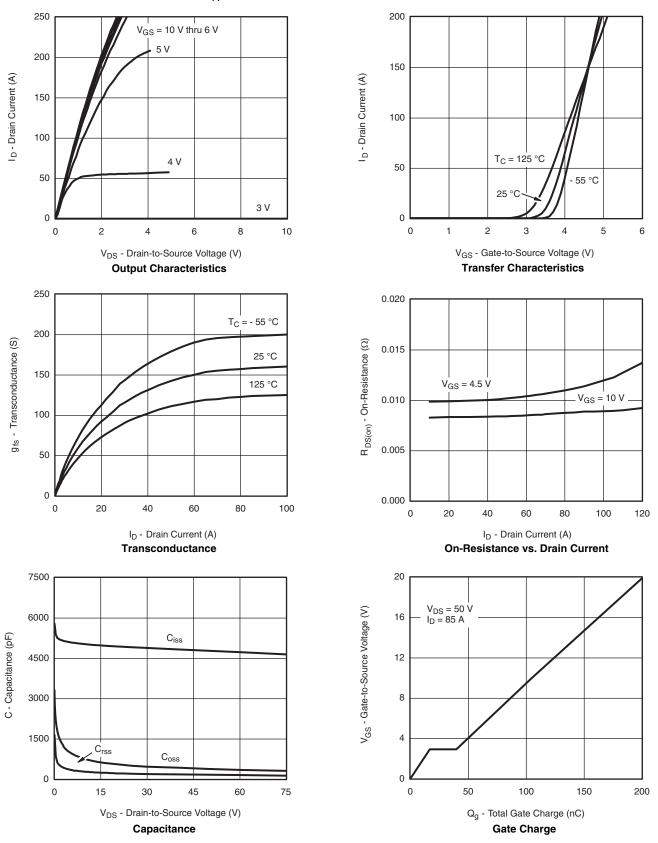
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- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

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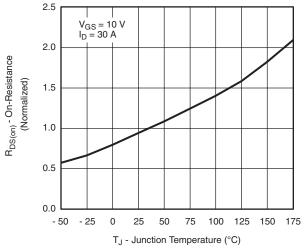


TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted

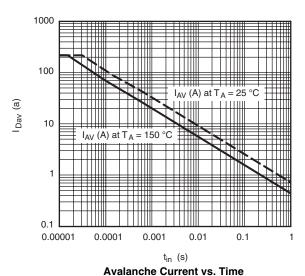




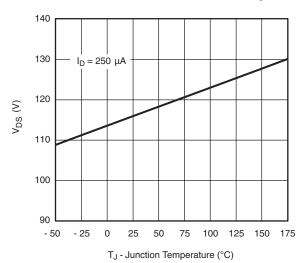
TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



On-Resistance vs. Junction Temperature



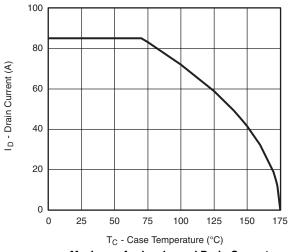
Source-Drain Diode Forward Voltage

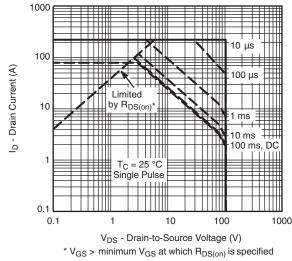


T_J - Drain-Source Breakdown vs. Junction-Temperature



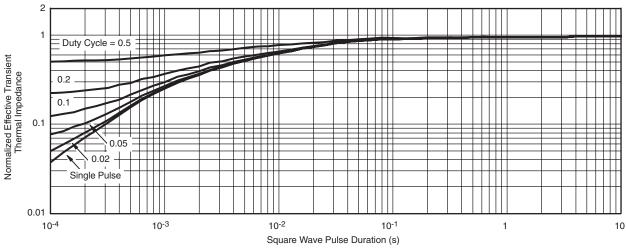
THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature

Safe Operating Area



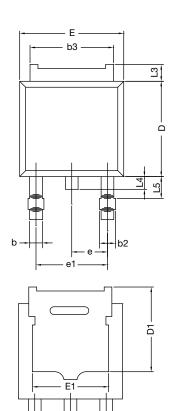
Normalized Thermal Transient Impedance, Junction-to-Case

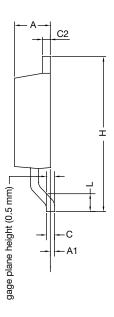
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TO-252AA CASE OUTLINE





	MILLIMETERS		INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090	BSC		
e1	4.56 BSC		0.180	BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12						

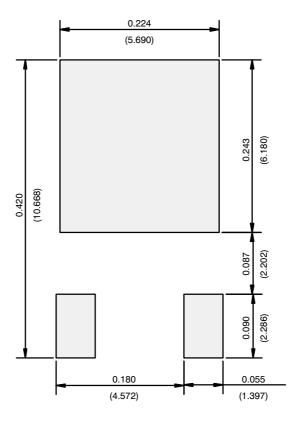
ECN: X12-0247-Rev. M, 24-Dec-1 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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